

# SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

24.04.2026



WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: Pinlamination

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1	A00 B00
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	108		2	
B-RaS-FR4-DS-1.194mm-018+018-TG150-HF...	50203144	35	L2	3	
		1158			
		35	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	108		4	
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	5	

Thickness after Pressing

B00: 1440 µm Tol+: 155 µm Tol-: 155 µm Dmax: 1595 µm Dmin: 1285 µm

Thickness over all

0 µm Tol+: 0 µm Tol-: 0 µm Dmax: 0 µm Dmin: 0 µm

Demand for customer

Thickness (D): 1550 µm Tol+: 155 µm Tol-: 155 µm Dmax: 1705 µm Dmin: 1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 1462 µm

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